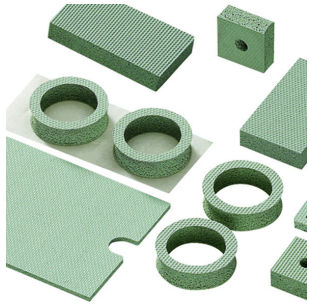


Data sheet Product WSF 32



Accessories for electronic components>Thermal interface material>Heat conductive foam and gel foils

- elastomer foam with closed cell structure
- good heat conductor e.g. between components, heatsinks and casing parts
- electrical insulating
- can be compressed even with a low contact pressure
- absorbs shocks and vibrations

Thermal resistance at 3.2 mm material thickness:

compression [%]	contact	10	25	50
contact pressure [psi]	>1	5	12	34
R_{th} [K/W] (1 in ² x 3.2 mm)	6	4.5	2.5	1
heat conductivity [W/mK]	0.3	0.4	0.45	0.65

- **WSFS 635** double sided adhesive and **WSF** self-adhesive upon request
- according to NASA gas emission requirements

Features

material:

foam film

Material:

10mm 11111

material thickness:

3.2^{±0,800} mm

version:

non adhesive

colour:

green

density:

1.105 g/cm³

hardness:

13 Shore A

temperature range:

-62°C ... +205°C

thermal conductivity:

0.108 W/m·K (substrate)

compression, 25%:

18 psi

elongation:

150 %

tear strength:

120 psi

dielectric strength:

4 kV/mm

class of inflammability:

UL 94 V-1 (at thickness ≥3.2mm)

type of delivery:

- **plates, usable area 914x914mm**
- **other dimensions upon request**